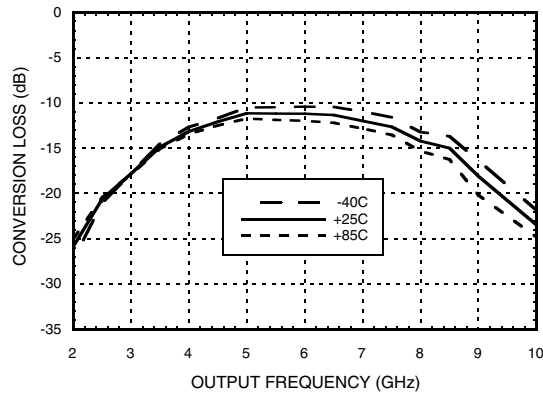


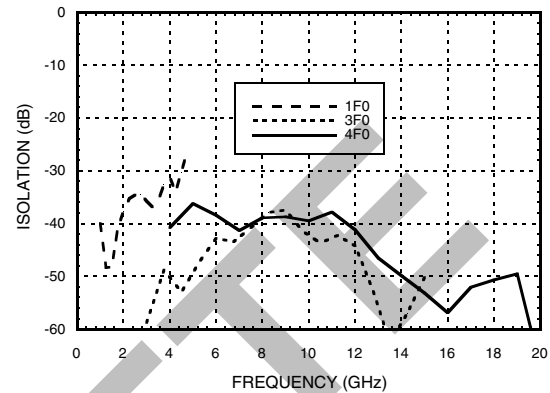


**GaAs MMIC SMT PASSIVE FREQUENCY
DOUBLER, 2 - 4 GHz INPUT**

Conversion Loss @ +13 dBm Drive Level

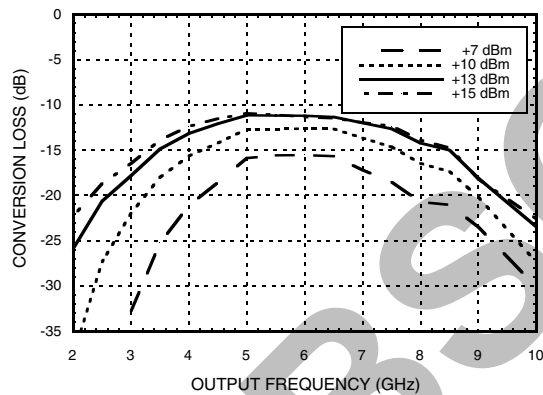


Isolation* @ +13 dBm Drive Level

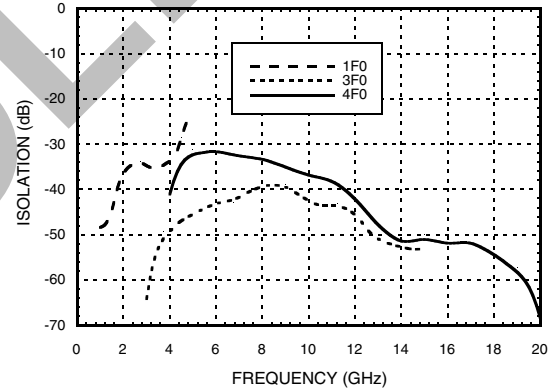


* With respect to input level

Conversion Loss vs. Drive Level

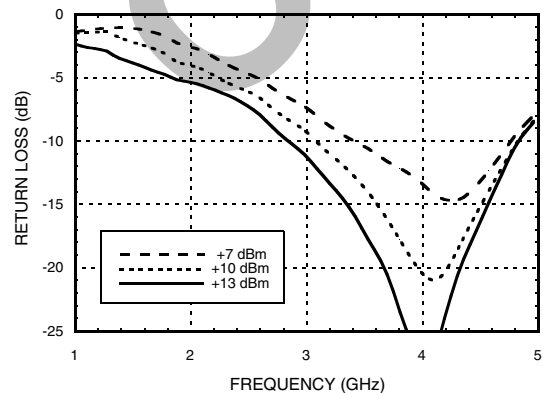


Isolation* @ +10 dBm Drive Level

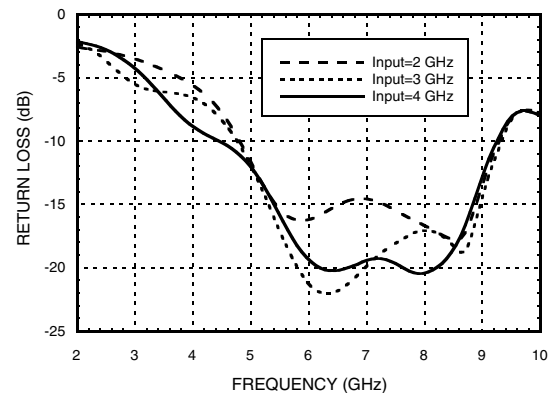


* With respect to input level

Input Return Loss vs. Drive Level



**Output Return Loss for
Several Input Frequencies**





GaAs MMIC SMT PASSIVE FREQUENCY DOUBLER, 2 - 4 GHz INPUT

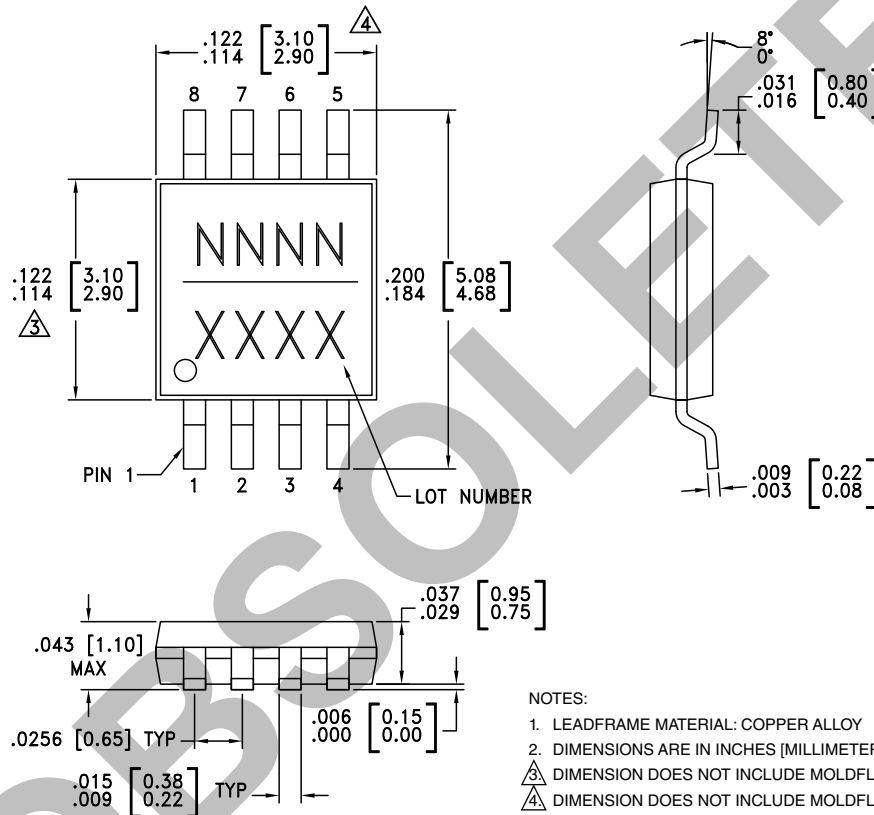
Absolute Maximum Ratings

Input Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1B



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Outline Drawing



Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC189AMS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	189A XXXX
HMC189AMS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	189A XXXX

[1] Max peak reflow temperature of 235 °C

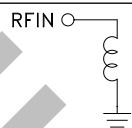

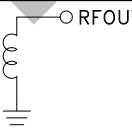
[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

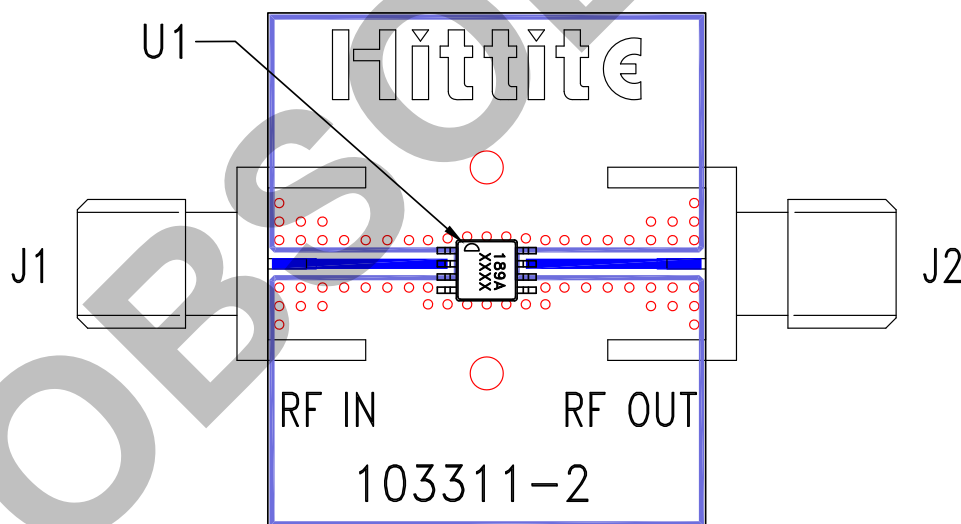


GaAs MMIC SMT PASSIVE FREQUENCY DOUBLER, 2 - 4 GHz INPUT

Pin Description

Pin Number	Function	Description	Interface Schematic
1, 4, 5, 8	N/C	These pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
2	RFIN	Pin is DC coupled and matched to 50 Ohms from 2.0 to 4.0 GHz	
3, 6	GND	All ground leads must be soldered to PCB RF/DC ground.	
7	RFOUT	Pin is DC coupled and matched to 50 Ohms from 4.0 to 8.0 GHz	

Evaluation PCB



List of Materials for Evaluation PCB 103313 ^[1]

Item	Description
J1, J2	PCB Mount SMA Connector
U1	HMC189AMS8(E) Doubler
PCB [2]	103311 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 ohm impedance and the package ground leads should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.